

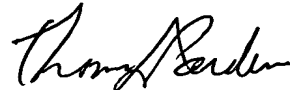
REMARKS

Claims 1-5 remain pending in this application. The attached Appendix includes marked-up copies of each rewritten paragraph (37 C.F.R. §1.121(b)(1)(iii)).

In response to the Notice of Omitted Items mailed July 23, 2001, and the Decision Dismissing the July 30, 2001 Petition, Applicant submits this Preliminary Amendment to eliminate references to Figure 9. This Amendment is submitted without prejudice to resubmission of Figure 9 during prosecution of this application. It is respectfully submitted that reinsertion of Figure 9 will not introduce new matter and the subject matter of Figure 9 is adequately described in the present specification at pages 9-10 and 27-28.

In addition, attached is a Request for Approval of Drawing Corrections in which Figures 10-13B are renumbered as Figures 9-12B.

Respectfully submitted,



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Attachment:
Appendix
Request for Approval of Drawing Corrections

JAO:TJP/jfm

Date: October 12, 2001

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<p>DEPOSIT ACCOUNT USE AUTHORIZATION Please grant any extension necessary for entry; Charge any fee due to our Deposit Account No. 15-0461</p>
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APPENDIX

Changes to Specification:

Page 9, lines 20-23 are deleted.

The following is a marked-up version of the amended paragraphs:

Page 9, line 24 - page 10, line 17:

Fig. ~~109~~10 shows an explanatory figure for explanation of the procedure for measurement of the degree of planarity of a surface 98 of a carrier ~~of Fig. 9~~18 utilizing the carrier shape measurement device according to the first embodiment of the present invention.

Fig. ~~1110~~110 shows an explanatory figure for explanation of an example of the situation and the measurement position when semiconductor wafers 97 are loaded into the carrier ~~of Fig. 9~~18.

Fig. ~~1211~~121 shows a flow chart showing the operation for measuring the degree of planarity of the surface 98 of the carrier 18 ~~of Fig. 9~~ utilizing the carrier shape measurement device according to the first embodiment of the present invention.

Fig. ~~13A12A~~12A shows, for the carrier shape measurement device according to the first embodiment of the present invention, an explanatory figure showing a structure in which a gap 49 can easily occur in a dustproof sheet 14; Fig. ~~13B12B~~12B shows another explanatory structure for preventing loosening of the dustproof sheet 14.

Page 27, line 14 - page 28, line 18:

Now, the structure of a FOUP type carrier 18 which is the subject of measurement by this carrier shape measurement device according to the first embodiment of the present invention will be explained in detail ~~with reference to Fig. 9~~. FOUP (Front Opening Unified Pod) is a carrier shape which is specified by the SEMI standard, and it is a carrier of the sealed type which receives wafers of 300 mm diameter. In concrete terms, the FOUP carrier 18 comprises a main body 91 which has an aperture only at its front surface, and a door 92

which is for closing this aperture. On both the side surfaces of the inside of the main body 91 there are provided a plurality of projections, i.e., of so-called teeth 93, with fixed spaces between them. Both the edges of wafers of 300 mm diameter are supported by these teeth 93 as shown in Fig. 11. Further, three concave members (not shown in the figures) are provided upon the bottom surface of the main body 91. A kinematic coupling according to the SEMI standard is implemented by these three concave members engaging with the pins 20a, 20b and 20c of the kinematic plate 20 of the stage 12.

Further, the door 92 of the FOUP type carrier 18 is provided with registration pin holes 96 for positioning the door 92, and with latch key holes 95 for keeping the door 92 in the unlocked state or in the locked state. When the door 92 is opened, first, positioning of the door 92 is performed by registration pins of a loading port being inserted into the registration pin holes 96, and then, after the door 92 has been put into the unlocked state by latch keys being inserted into the latch key holes and being rotated, the door 92 is separated from the main body 91 by the load port pulling the door 92 forward to itself, as shown in Fig. 9.